



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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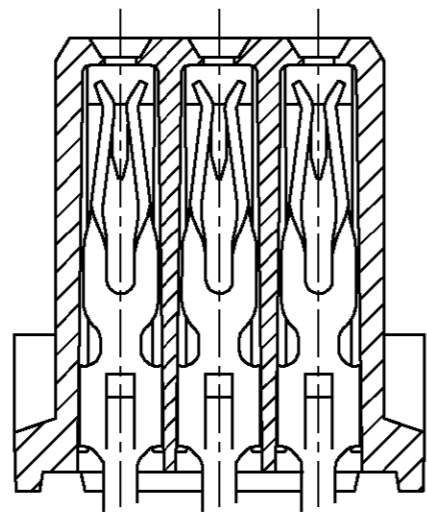
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



P.C.B. HOLE DIM. ACTION PIN

DRILLED HOLE	1,15 ±0,025	mm
FIN. HOLE	0,94 to 1,09	mm
AFTER REFLOW	0,91 to 1,09	mm
Cu-thks	0,025 to 0,075	mm
SnPb-thks	0,004 to 0,010	mm

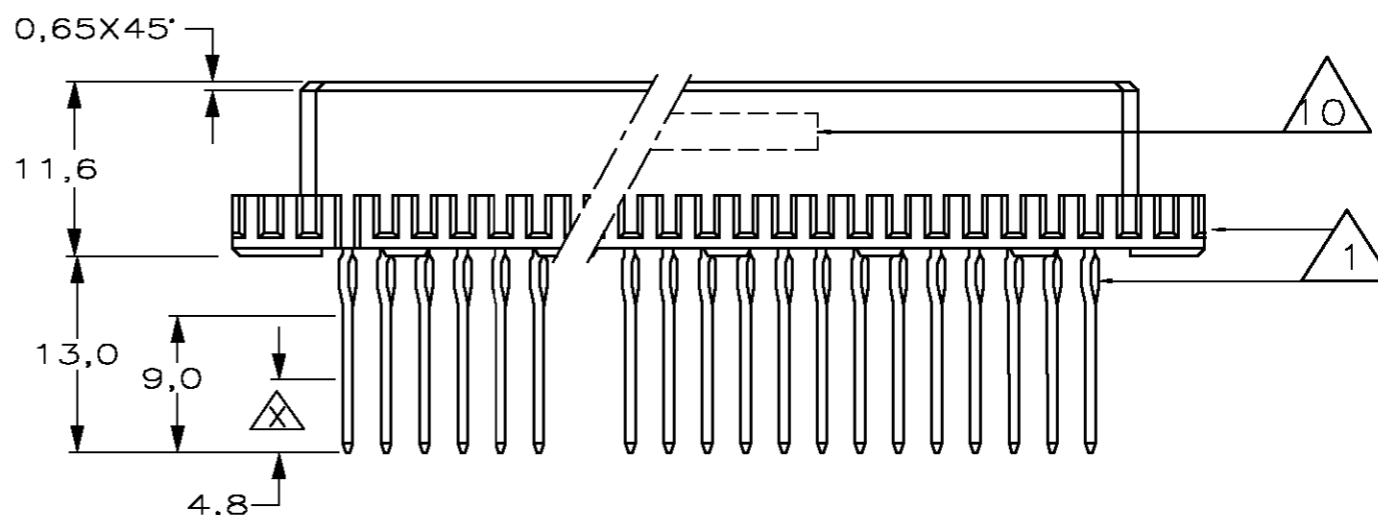
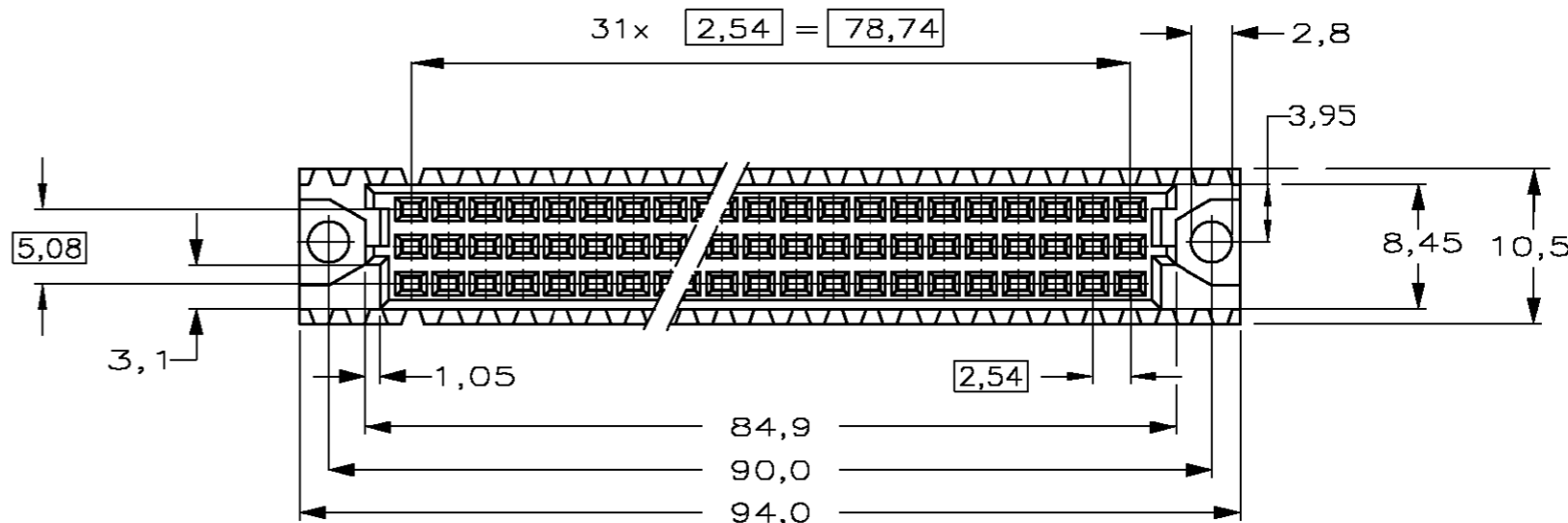
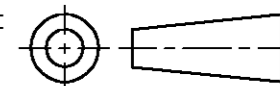


DO NOT SCALE

DIMENSIONS IN mm

METRIC

THIRD ANGLE PROJECTION



NOTES:

- 1 CONNECTOR MEETS THE REQUIREMENTS ACC. IEC 603-2 AND DIN 41611, PART 2 AND 5.
- 2 MATERIAL CONTACT: COPPER ALLOY. MATERIAL HOUSING: GLASSFILLED THERM. POLYESTER.
- 3 AT CONTACT AREA Au OVER Ni PERFORMANCE LEVEL I ACC. IEC 603-2. REMAINDER TIN-LEAD.
- 4 AT CONTACT AREA Au OVER Ni PERFORMANCE LEVEL II ACC. IEC 603-2. REMAINDER TIN-LEAD.
- 5 AT CONTACT AREA AND AREA Δ Au OVER Ni PERFORMANCE LEVEL I AT ACTION-PIN AREA TIN-LEAD.
- 6 AT CONTACT AREA AND AREA Δ Au OVER Ni PERFORMANCE LEVEL II AT ACTION-PIN AREA TIN-LEAD.
- 7 AT CONTACT AREA AND AREA Δ Au OVER Ni PERFORMANCE LEVEL III AT ACTION-PIN AREA TIN-LEAD.
- 8 AT CONTACT AREA AND AREA Δ Au OVER Pd OVER Ni PERFORMANCE LEVEL II AT ACTION PIN AREA TIN-LEAD.
- 9 AT CONTACT AREA AND AREA Δ Au OVER Pd OVER Ni PERFORMANCE LEVEL III AT ACTION PIN AREA TIN-LEAD.
- 10 CONNECTOR PRINTED WITH PARTNUMBER AND DATECODE ON OUTSIDE OF MATING AREA OF ROW c.
- 11 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

ROW	c	XX
d	b	XX
d	a	XX
POS		31 30 29 28 27 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1

AN ASTERISK „X” DENOTES A SIGNAL CONTACT.

OBSOLETE	9	2	7-215912-8
OBSOLETE	8	2	7-215912-4
OBSOLETE	7	2	1-215912-8
SUPERSEDED BY 1-148057-5	6	2	1-215912-4
11 OBSOLETE	5	2	1-215912-1
SUPERSEDED BY 5148057-5	4	2	215912-4
OBSOLETE	3	2	215912-1

				FINISH	MATERIAL	PARTNUMBER
H3	ECR-11-008320	RK	MKO	18NOV11	CUSTOMER DRAWING FOR REFERENCE ONLY WILL NOT BE UPDATED	
H2	ECR-10-024793	RK	MKO	14OCT11	© COPYRIGHT 20 - BY TE EC N.V. ALL INTERNATIONAL RIGHTS RESERVED. TE PRODUCTS MAY BE COVERED BY U.S. AND FOREIGN AND/OR PATENTS PENDING. THIS DRAWING IS UNPUBLISHED RELEASED FOR PUBLICATION .19	
H1	ECO-09-024717	KK	AEG	29DEC09	TE Connectivity	
H	SR10-0013-02	BC	BC	8 Jan '02	NAME 96 POS FEMALE CONN. ASS'Y ACC. IEC 603-2 WITH ACTION-PIN FOR 2,4-3,2mm P.C.BOARD THK'S	
F1	EH00-1209-00	RvH	R.F.	08-11-00	REV.LTR. H3 SHEET 1 OF 1 A3	
F	EH-0855-97	J.G.	J.G.	06-08-97	DWG.No. C-215912	
E	EH0268-94	R.v.L	J.v.G	19.04.94	DATE: _____	
LTR.	REVISION RECORD	DR.	CHK.	DATE	DATE: _____	
DR.:	Colpaert B.	CHK.:	Colpaert B.	APP.:	Colpaert B.	DATE: _____